

Title: Flip chip interconnection structure

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Appln. No. 09/802,664

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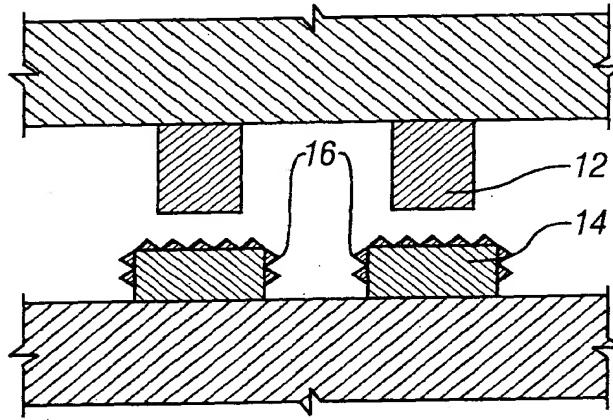


FIG. 1A

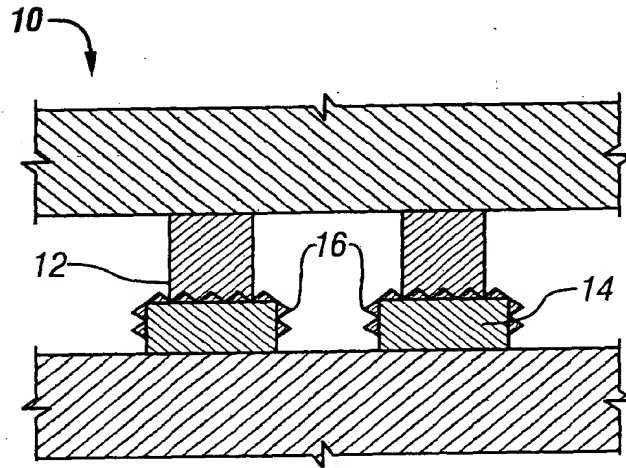


FIG. 1B

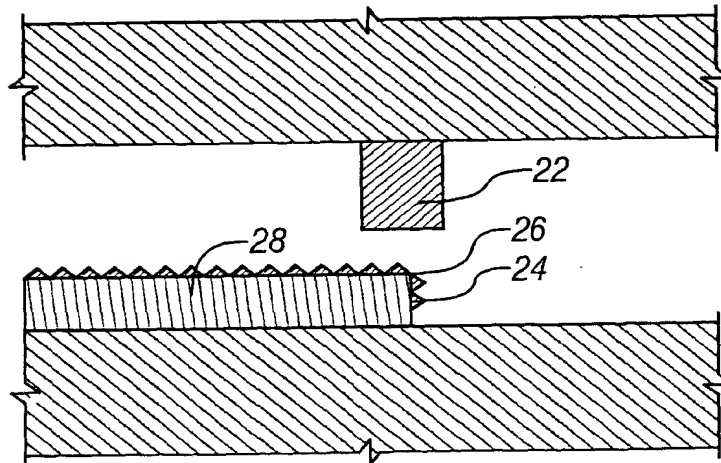


FIG. 2A

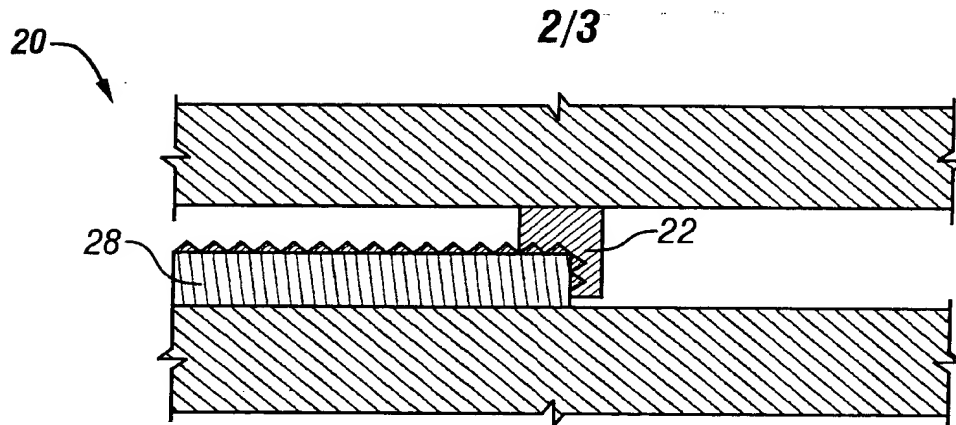


FIG. 2B

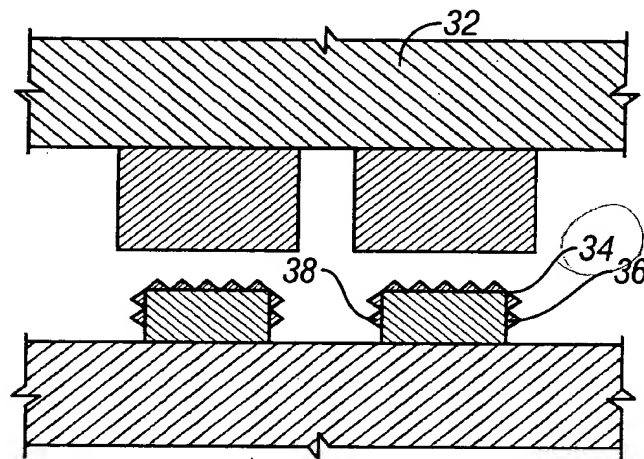


FIG. 3A

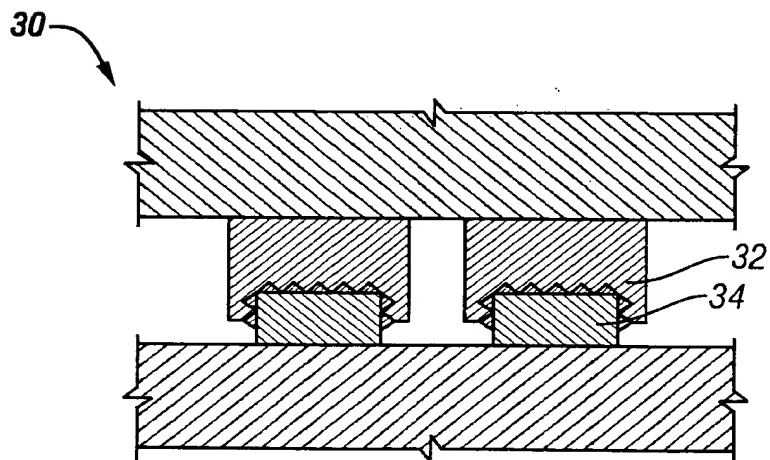


FIG. 3B

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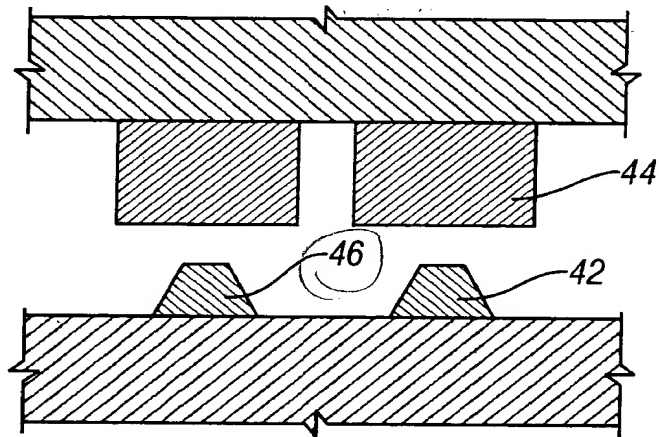


FIG. 4A

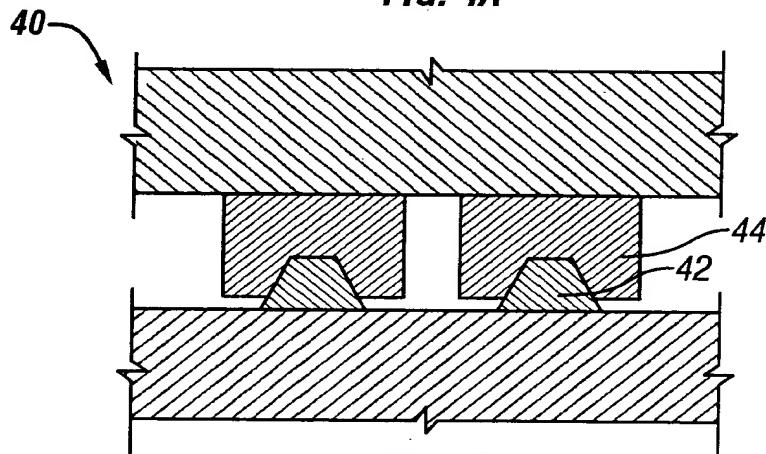


FIG. 4B

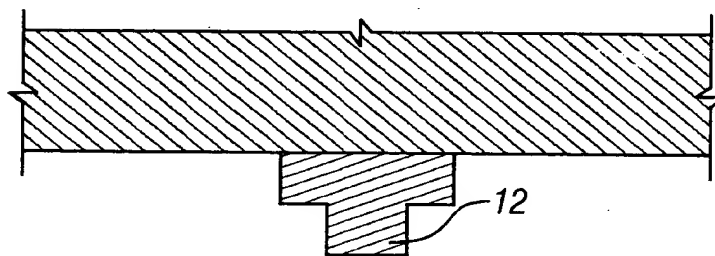


FIG. 5

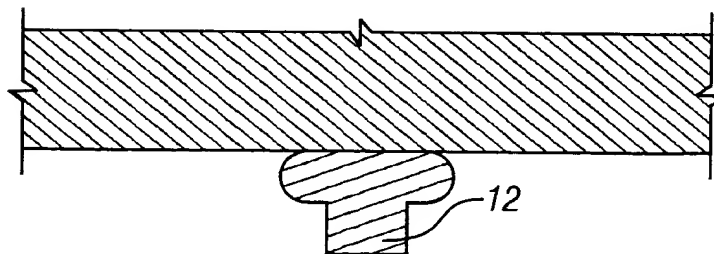


FIG. 6